



**THE DATASHEET OF
CSD16321Q5**



CSD16321Q5 25V N-Channel NexFET™ Power MOSFET

1 Features

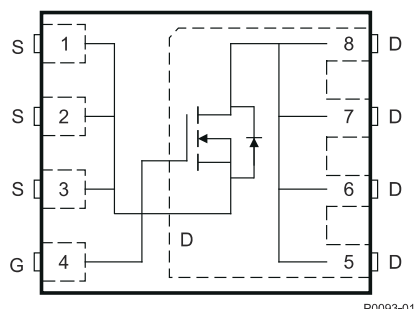
- Optimized for 5V gate drive
- Ultra-low Q_g and Q_{gd}
- Low-thermal resistance
- Avalanche rated
- Lead-free terminal plating
- RoHS compliant
- SON 5mm × 6mm plastic package

2 Applications

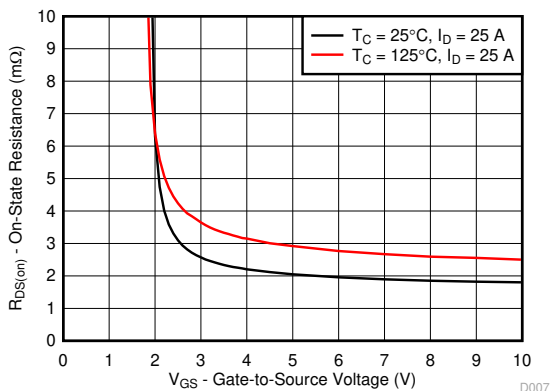
- Point-of-load synchronous buck converter for applications in networking, telecom, and computing systems
- Optimized for synchronous FET applications

3 Description

This 25V, 1.9mΩ, 5mm × 6mm SON NexFET™ power MOSFET has been designed to minimize losses in power conversion and optimized for 5V gate drive applications.



Top View



$R_{DS(ON)}$ vs V_{GS}

Product Summary

$T_A = 25^\circ\text{C}$		TYPICAL VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	25	V
Q_g	Gate Charge Total (4.5V)	14	nC
Q_{gd}	Gate Charge Gate-to-Drain	2.5	nC
$R_{DS(on)}$	Drain-to-Source On Resistance	$V_{GS} = 3\text{V}$	2.8
		$V_{GS} = 4.5\text{V}$	2.1
		$V_{GS} = 8\text{V}$	1.9
$V_{GS(th)}$	Threshold Voltage	1.1	V

Device Information⁽¹⁾

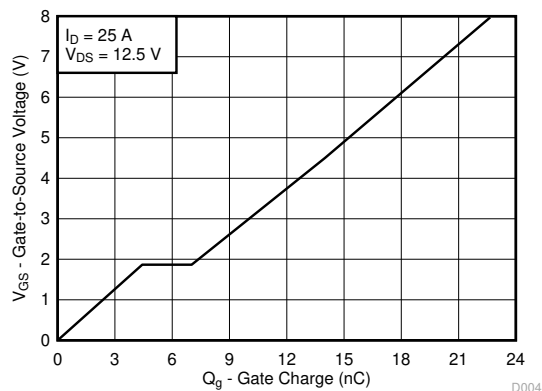
DEVICE	MEDIA	QTY	PACKAGE	SHIP
CSD16321Q5	13-Inch Reel	2500	SON 5.00mm × 6.00mm Plastic Package	Tape and Reel
CSD16321Q5T	7-Inch Reel	250		

- (1) For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	25	V
V_{GS}	Gate-to-Source Voltage	+10 / -8	V
I_D	Continuous Drain Current (Package Limited)	100	A
	Continuous Drain Current (Silicon Limited), $T_C = 25^\circ\text{C}$	177	
	Continuous Drain Current ⁽¹⁾	29	
I_{DM}	Pulsed Drain Current ⁽²⁾	400	A
P_D	Power Dissipation ⁽¹⁾	3.1	W
	Power Dissipation, $T_C = 25^\circ\text{C}$	113	
T_J , T_{stg}	Operating Junction, Storage Temperature	-55 to 150	$^\circ\text{C}$
E_{AS}	Avalanche Energy, Single Pulse $I_D = 66\text{A}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$	218	mJ

- (1) Typical $R_{\theta JA} = 40^\circ\text{C}/\text{W}$ on 1in², 2oz Cu pad on 0.06in thick FR4 PCB.
 (2) Max $R_{\theta JC} = 1.1^\circ\text{C}/\text{W}$, pulse duration $\leq 100\mu\text{s}$, duty cycle $\leq 1\%$.



Gate Charge



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4 Specifications

4.1 Electrical Characteristics

$T_A = 25^\circ\text{C}$ (unless otherwise stated)

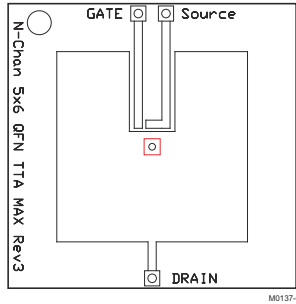
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV_{DSS}	Drain-to-source voltage	$V_{GS} = 0V, I_D = 250\mu A$	25			V
I_{DSS}	Drain-to-source leakage current	$V_{GS} = 0V, V_{DS} = 20V$			1	μA
I_{GSS}	Gate-to-source leakage current	$V_{DS} = 0V, V_{GS} = +10 / -8V$			100	nA
$V_{GS(th)}$	Gate-to-source threshold voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.9	1.1	1.4	V
$R_{DS(on)}$	Drain-to-source on resistance	$V_{GS} = 3V, I_D = 25A$		2.8	3.8	m Ω
		$V_{GS} = 4.5V, I_D = 25A$		2.1	2.6	
		$V_{GS} = 8V, I_D = 25A$		1.9	2.4	
g_{fs}	Transconductance	$V_{DS} = 12.5V, I_D = 25A$		150		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input capacitance	$V_{GS} = 0V, V_{DS} = 12.5V, f = 1MHz$		2360	3100	pF
C_{oss}	Output capacitance			1700	2200	pF
C_{riss}	Reverse transfer capacitance			115	150	pF
R_G	Series gate resistance			1.5	3	Ω
Q_g	Gate charge total (4.5 V)	$V_{DS} = 12.5V, I_D = 25A$		14	19	nC
Q_{gd}	Gate charge gate-to-drain			2.5		nC
Q_{gs}	Gate charge gate-to-source			4		nC
$Q_{g(th)}$	Gate charge at V_{th}			2.1		nC
Q_{oss}	Output charge	$V_{DS} = 15V, V_{GS} = 0V$		36		nC
$t_{d(on)}$	Turnon delay time	$V_{DS} = 12.5V, V_{GS} = 4.5V, I_D = 25A, R_G = 2\Omega$		9		ns
t_r	Rise time			15		ns
$t_{d(off)}$	Turnoff delay time			27		ns
t_f	Fall time			17		ns
DIODE CHARACTERISTICS						
V_{SD}	Diode forward voltage	$I_{SD} = 25A, V_{GS} = 0V$		0.8	1	V
Q_{rr}	Reverse recovery charge	$V_{DD} = 13V, I_F = 25A, di/dt = 300A/\mu s$		33		nC
t_{rr}	Reverse recovery time	$V_{DD} = 13V, I_F = 25A, di/dt = 300A/\mu s$		32		ns

4.2 Thermal Information

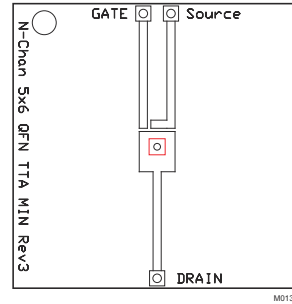
$T_A = 25^\circ\text{C}$ (unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-case thermal resistance ⁽¹⁾			1.1	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-ambient thermal resistance ^{(1) (2)}			50	$^\circ\text{C}/\text{W}$

- $R_{\theta JC}$ is determined with the device mounted on a 1in², 2oz Cu pad on a 1.5in × 1.5in, 0.06in thick FR4 board. $R_{\theta JC}$ is specified by design while $R_{\theta JA}$ is determined by the user's board design.
- Device mounted on FR4 Material with 1 in² of 2oz Cu.



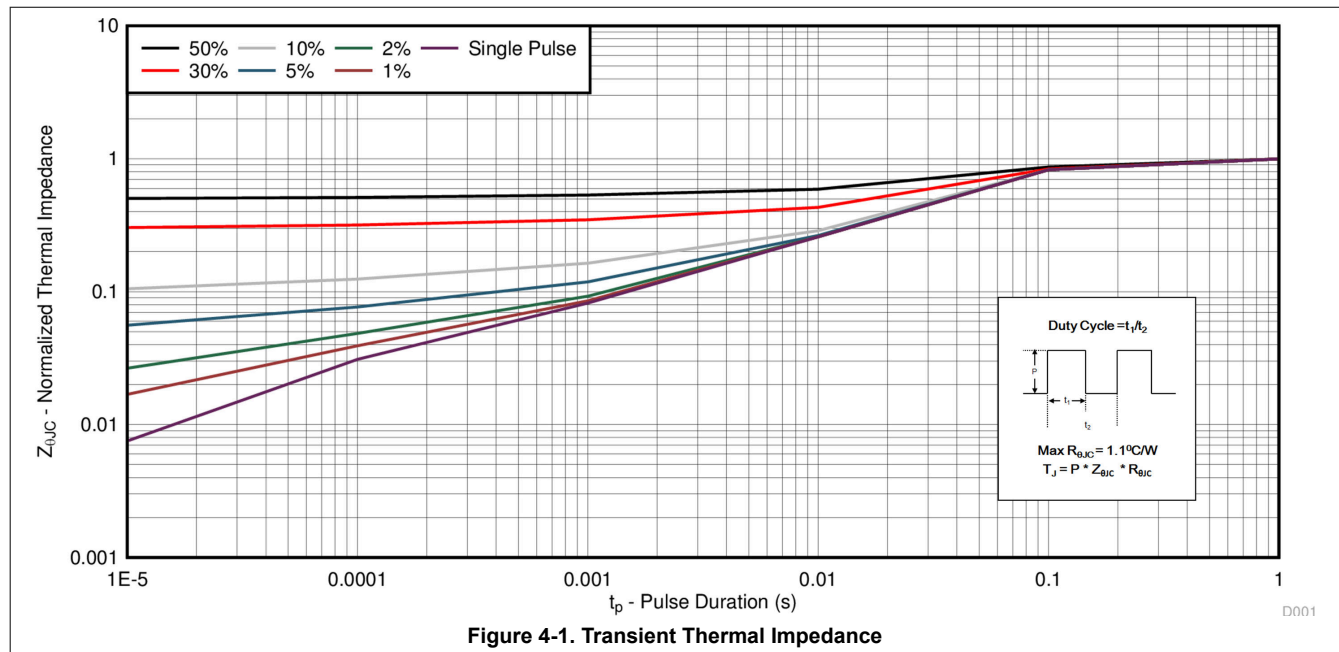
Max $R_{\theta JA}$ = 50°C/W when mounted on 1in² of 2oz Cu.



Max $R_{\theta JA}$ = 125°C/W when mounted on minimum pad area of 2oz Cu.

4.3 Typical MOSFET Characteristics

T_A = 25°C (unless otherwise stated)



4.3 Typical MOSFET Characteristics (continued)

$T_A = 25^\circ\text{C}$ (unless otherwise stated)

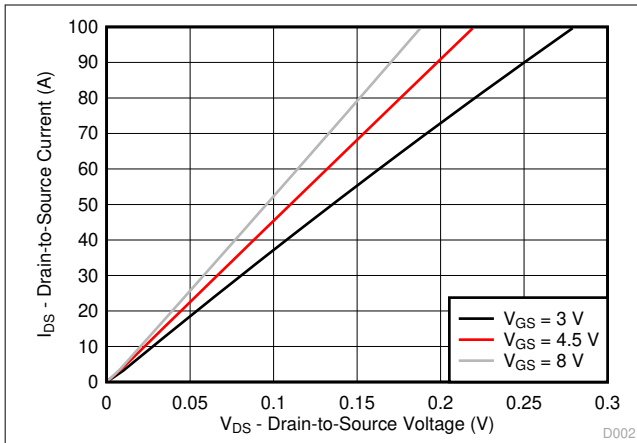


Figure 4-2. Saturation Characteristics

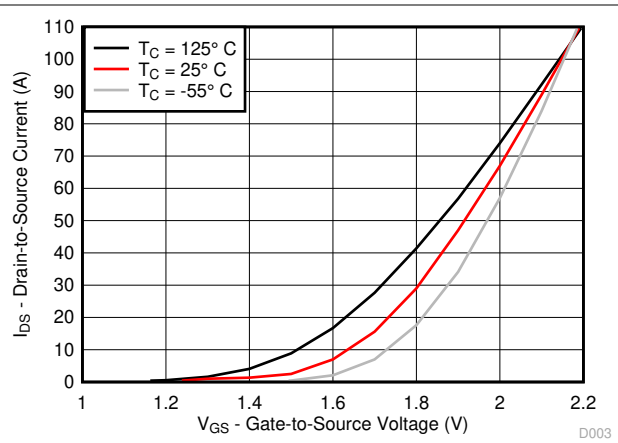


Figure 4-3. Transfer Characteristics

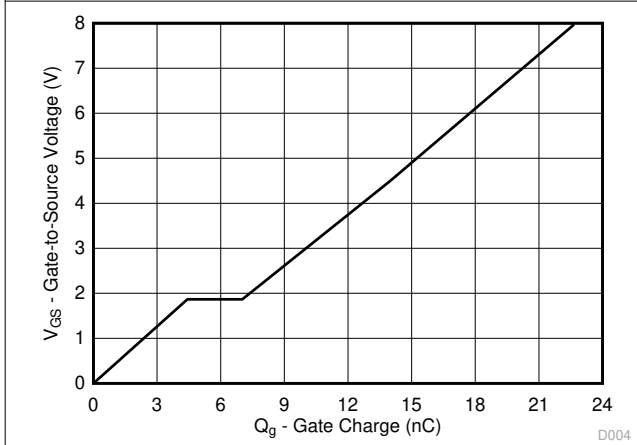


Figure 4-4. Gate Charge

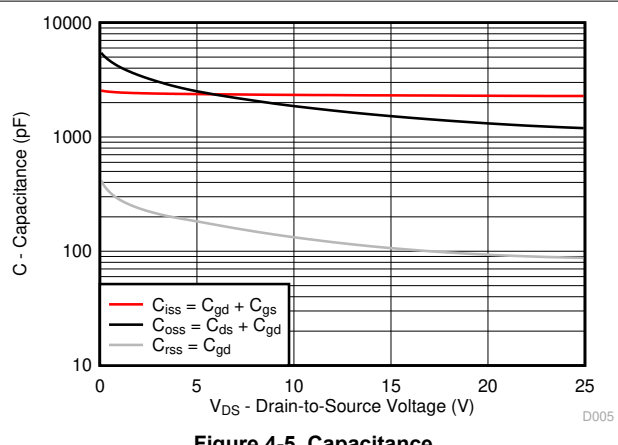


Figure 4-5. Capacitance

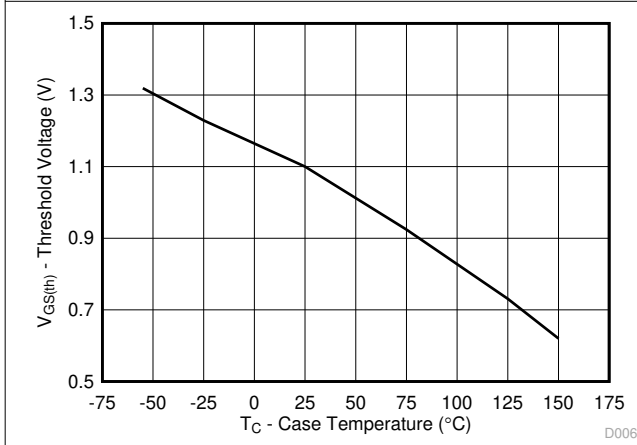


Figure 4-6. Threshold Voltage vs Temperature

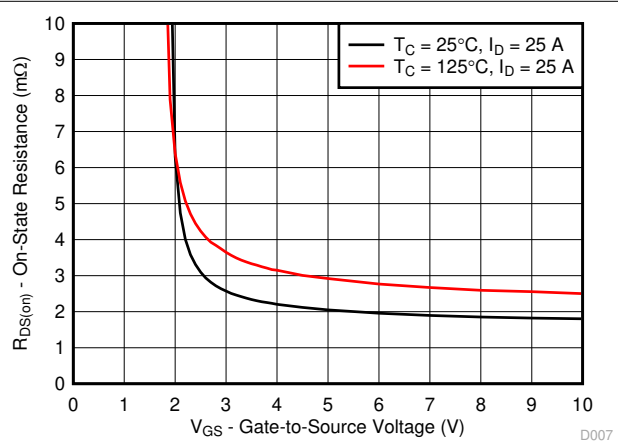
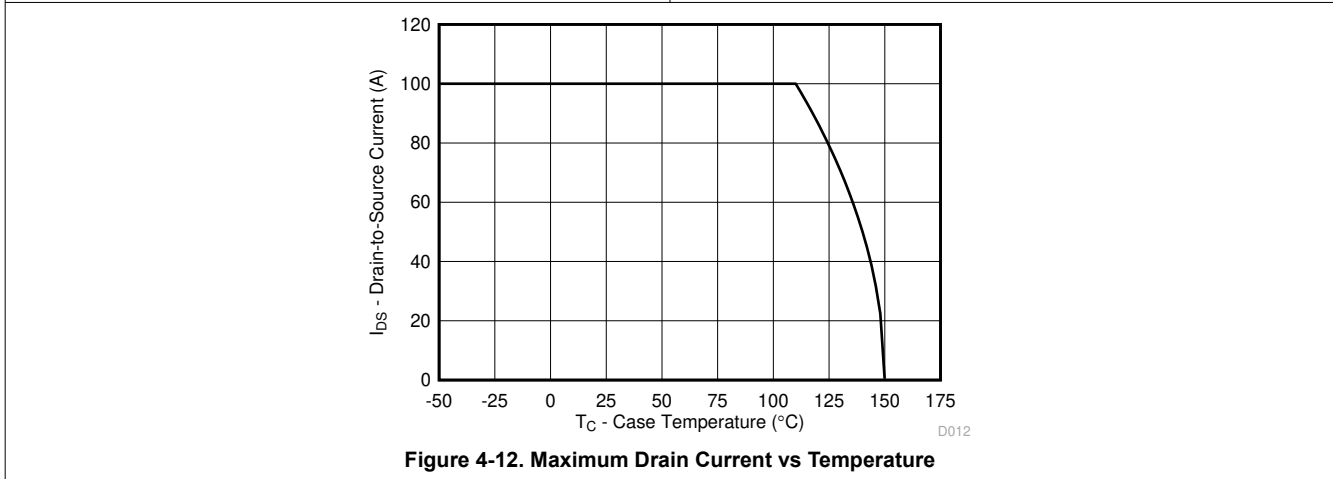
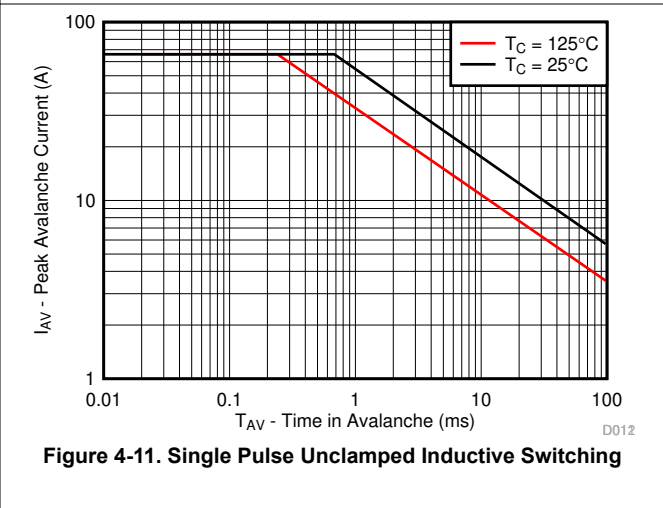
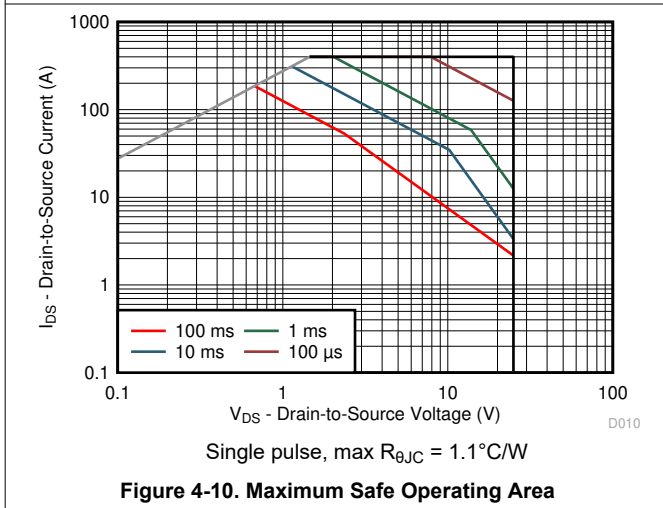
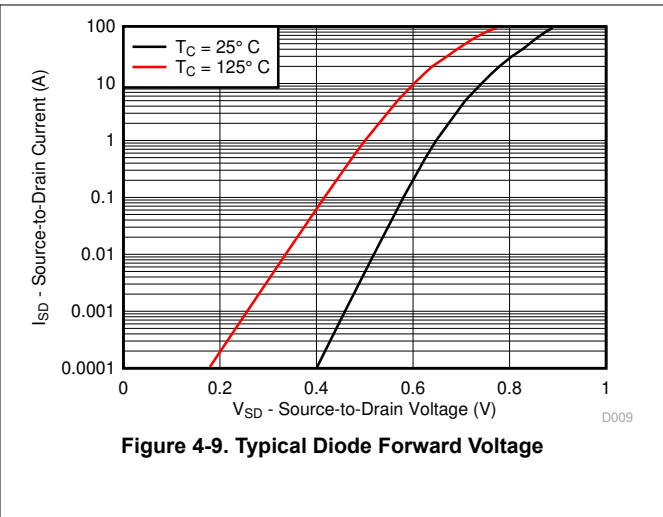
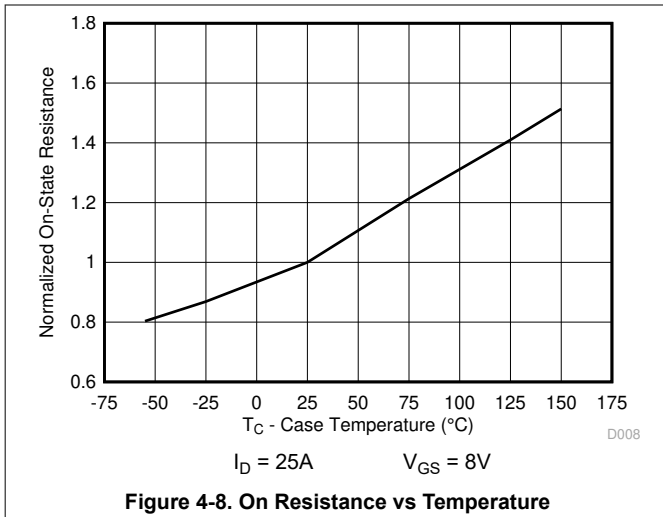


Figure 4-7. On Resistance vs Gate Voltage

4.3 Typical MOSFET Characteristics (continued)

T_A = 25°C (unless otherwise stated)



5 Device and Documentation Support

5.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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5.3 Trademarks

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5.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

6 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (May 2017) to Revision E (December 2023)	Page
<ul style="list-style-type: none"> • Updated the numbering format for tables, figures, and cross-references throughout the document..... 1 	1
<hr/>	
Changes from Revision C (December 2016) to Revision D (May 2017)	Page
<ul style="list-style-type: none"> • Changed the $R_{DS(ON)}$ values at 3 V, 4.5 V, 8 V & the <i>Description</i> to match the values on the <i>Electrical Characteristics</i> table. 1 	1
<hr/>	
Changes from Revision B (May 2010) to Revision C (December 2016)	Page
<ul style="list-style-type: none"> • Changed <i>Description</i> text..... 1 • Added silicon limited continuous drain current to <i>Absolute Maximum Ratings</i> table.....1 • Added max power dissipation at $T_C = 25^\circ\text{C}$ to <i>Absolute Maximum Ratings</i> table.....1 • Changed Note 2 in <i>Absolute Maximum Ratings</i> table..... 1 • Changed $R_{\theta JA}$ max from 48°C/W : to 50°C/W.....3 • Changed the SOA in Figure 4-10 to reflect measured data..... 4 • Changed <i>MECHANICAL DATA</i> section to <i>Mechanical, Packaging, and Orderable Information</i> section.....9 	9
<hr/>	
Changes from Revision A (January 2010) to Revision B (May 2010)	Page
<ul style="list-style-type: none"> • Changed $R_{DS(on)} - V_{GS} = 3\text{V}$, $I_D = 25\text{A}$ MAX value From: 3.5 To: 3.8..... 3 	3
<hr/>	
Changes from Revision * (August 2009) to Revision A (January 2010)	Page
<ul style="list-style-type: none"> • Changed the labels on the Top View pinout image..... 1 • Changed Note 1 of the <i>Absolute Maximum Ratings</i> From: $R_{\theta JA} = 39^\circ\text{C/W}$ To: Typical $R_{\theta JA} = 39^\circ\text{C/W}$..... 1 • Changed Figure 4-1 text From: $R_{\theta JA} = 92^\circ\text{C/W}$ To: Typical $R_{\theta JA} = 93^\circ\text{C/W}$..... 4 • Changed Figure 4-10 text From: $R_{\theta JA} = 92^\circ\text{C/W}$ To: Typical $R_{\theta JA} = 93^\circ\text{C/W}$..... 4 • Changed Figure 4-11 X-axis values..... 4 	4

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD16321Q5	ACTIVE	VSON-CLIP	DQH	8	2500	RoHS-Exempt & Green	SN	Level-1-260C-UNLIM	-55 to 150	CSD16321	Samples
CSD16321Q5T	ACTIVE	VSON-CLIP	DQH	8	250	RoHS-Exempt & Green	SN	Level-1-260C-UNLIM	-55 to 150	CSD16321	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

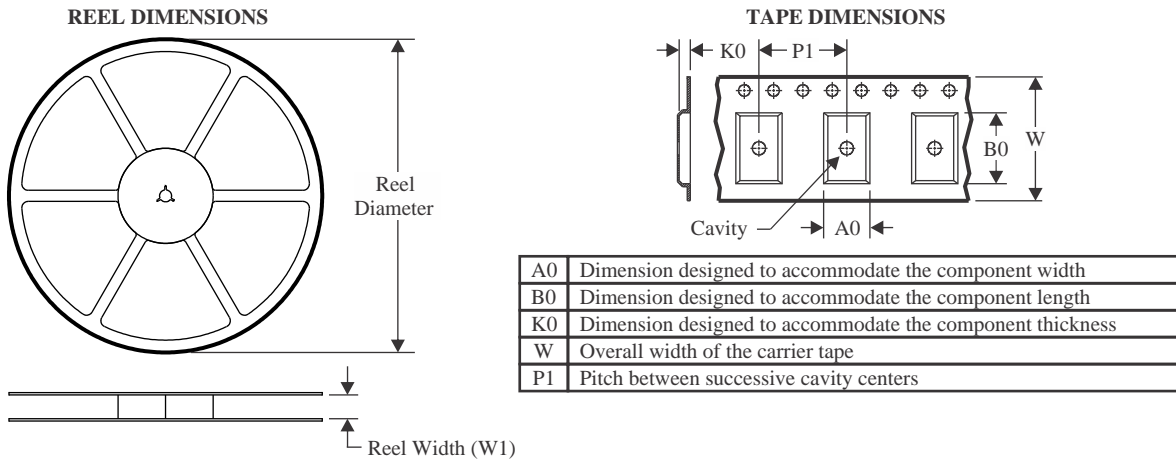
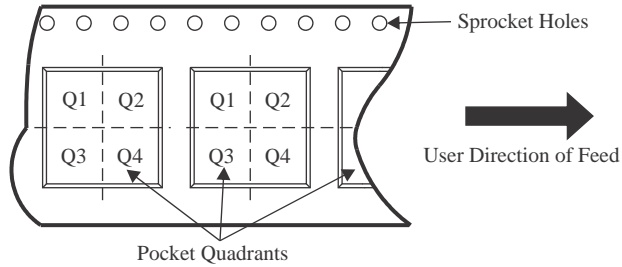
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD16321Q5T	VSON-CLIP	DQH	8	250	178.0	12.4	6.3	5.3	1.2	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD16321Q5T	VSON-CLIP	DQH	8	250	180.0	180.0	79.0

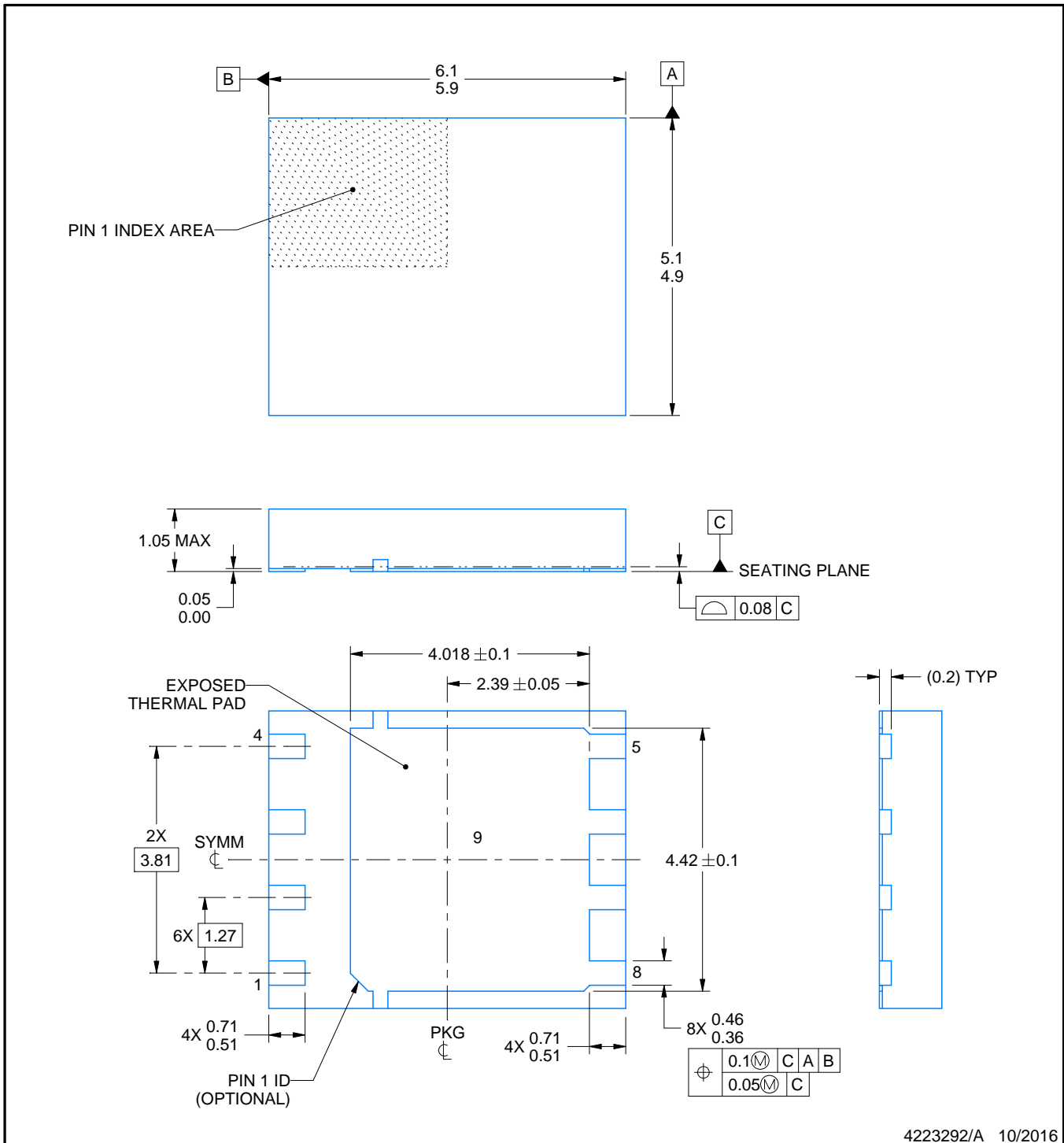
DQH0008A



PACKAGE OUTLINE

VSON-CLIP - 1.05 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

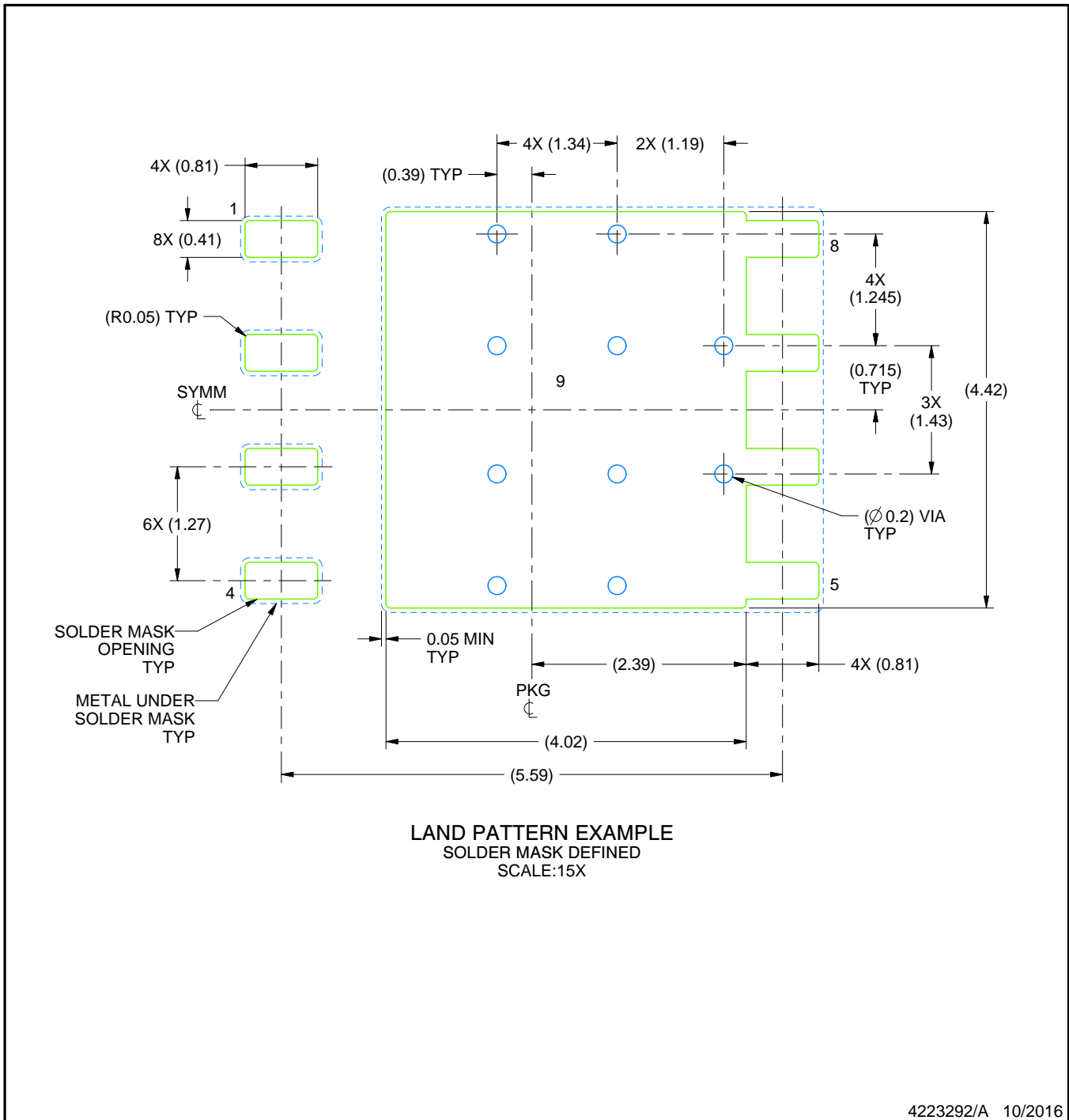
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

DQH0008A

VSON-CLIP - 1.05 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

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